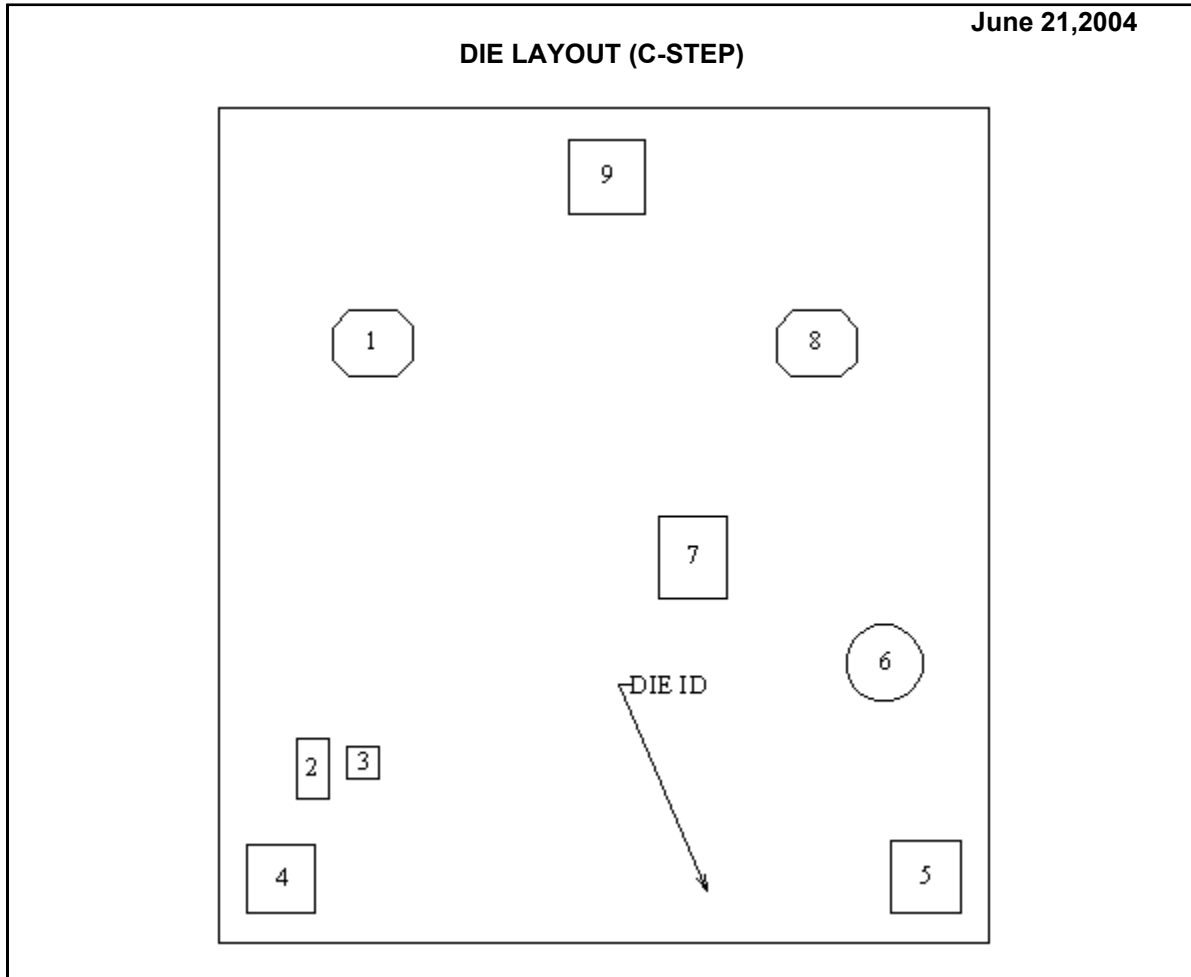


LM117HVKG MD8 MW8
3-TERMINAL ADJUSTABLE REGULATOR



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	117C	Bond Pad Opening Size (min)	229 μ m x 188 μ m
Die Step	C	Bond Pad Metalization	ALUMINUM
Physical Attributes		Passivation	VOM NITRIDE
Wafer Diameter	100 or 150mm	Back Side Metal	Gold
Die Size (Drawn)	2362 μ m x 2184 μ m 93.0mils x 86.0mils	Back Side Connection	OUTPUT
Thickness	254 μ m Nominal		
Min Pitch	146 μ m Nominal		

Special Assembly Requirements:

Note: Actual die size is rounded to the nearest micron.

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Die Bond Pad Coordinate Locations (C -Step)						
(Referenced to die center, coordinates in μm) NC = No Connection, N.U. = Not Used						
SIGNAL	PAD#	X/Y COORDINATES		PAD SIZE		
NAME	NUMBER	X	Y	X	Y	
OUTPUT	1	-655	516	229	x	188
NC	2	-827	-690	89	x	170
NC	3	-681	-673	91	x	91
OUTPUT	4	-914	-1001	193	x	198
ADJ	5	913	-997	196	x	206
NC	6	800	-391	208	x	208
INPUT	7	254	-91	193	x	234
OUTPUT	8	603	514	226	x	185
INPUT	9	10	987	213	x	211

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